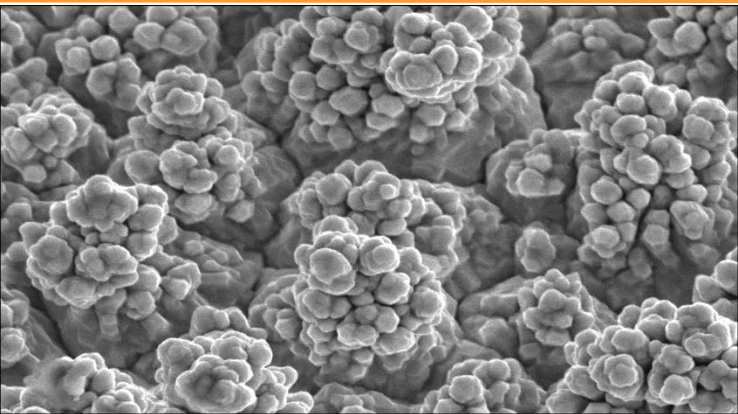


● Features

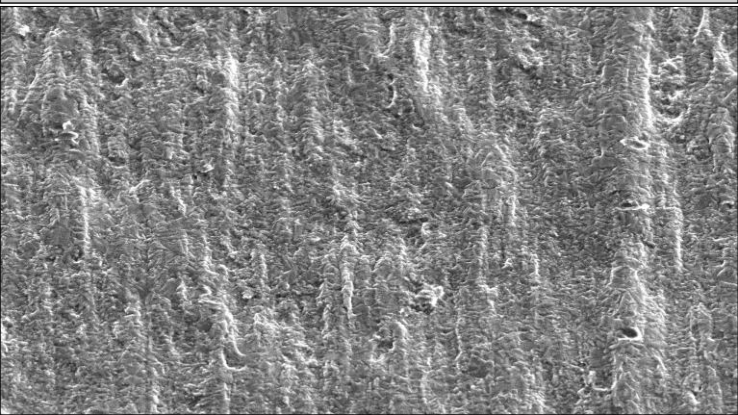
- Excellent peel strength, anti-oxidation and shelf life.
- Good etching ability for fine pitch process.
- Thin copper foil stable production capacity, can fully supply customer needs.

● Applications

- High speed server outer layer copper foil.
- Networking, Telecom, Server, Base station of Microstrip design
- Materials: FR4 resin, Low loss, Very low loss up.



18μm Foil Bonding-side SEM × 5,000



18μm Foil Resist-side SEM × 1,500

MEASURED PARAMETERS			UNITS	PRODUCT GAUGE					IPC	
Nominal Thickness			μm oz.	12 1/3	15 3/7	18 1/2	35 1	53 1.5	Specificat ion IPC- 4562A	Test Method IPC-TM- 650
Area Weight			g/m ²	107±3	125±5	153±5	285±8	435±8	3.4.4	2.2.12
Bonding Side Contact Roughness	Rz	JIS B 0601	μm	≤6.0	≤7.0	≤8.0	≤12.0	≤13.0	-	2.2.17
Resist Side Contact Roughness	Ra	JIS B 0601	μm	≤0.43					-	2.2.17
Tensile Strength		RT	MPa (Kgf/mm ²)	≥274 (≥28)				≥254 (≥26)	3.5.1	2.4.18
		180°C		≥167 (≥17)				≥147 (≥15)		
Elongation		RT	%	≥3.0	≥5.0	≥5.0	≥6.0	≥6.0	3.5.3	
		180°C		≥2.0	≥2.0	≥3.0	≥5.0	≥5.0		
Peel Strength with FR4 (Tg140°C) Resin (RT)			N/mm (lbf/in)	≥0.98 (≥5.6)	≥1.14 (≥6.5)	≥1.31 (≥7.5)	≥1.75 (≥10.0)	≥1.93 (≥11.0)	3.5.4	2.4.8

*The data above show actual values and are not guaranteed